

**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT**

JAN 26 2004

Attorney Docket Number 6884-65576

Application Number 10/688,420

Filing Date October 16, 2003

First Named Inventor John L. Klocke

Art Unit ~~Not yet assigned~~ 1753Examiner Name ~~Not yet assigned~~ E. Wang

U.S. PATENT DOCUMENTS

Examiner's Initials*	Cite No. (optional)	Number	Date	Name
Q		5,972,192	10/1999	Dubin et al.
		6,074,544	6/2000	Reid et al.
		6,290,833	9/2001	Chen
		6,331,490	12/2001	Stevens et al.
		6,409,892	6/2002	Woodruff et al.
		6,413,436	7/2002	Aegerter et al.
		6,491,806	12/2002	Dubin et al.
		6,508,920	1/2003	Ritzdorf et al.
		6,517,894	2/2003	Hongo et al.
		6,534,117	3/2003	Yoshio et al.
		6,565,729	5/2003	Chen et al.
		US 2002/0112964	8/2002	Gandikota et al.
		US 2004/0007467	1/2004	McHugh et al.

FOREIGN PATENT DOCUMENTS

Examiner's Initials*	Cite No. (optional)	Number	Date	Country

EXAMINER
SIGNATURE:

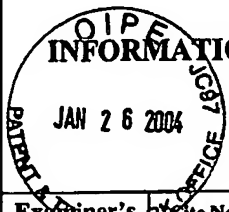

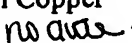

E. Wang

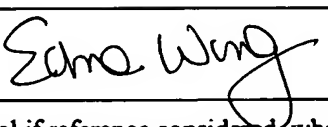
DATE

CONSIDERED:

11/14/05

* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.

 INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Attorney Docket Number	6884-65576
		Application Number	10/688,420
		Filing Date	October 16, 2003
		First Named Inventor	John L. Klocke
		Art Unit	Not yet assigned
		Examiner Name	Not yet assigned
Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS	
		Dordi, Yezdi et al., "Automated Chemical Management for Production Copper Electroplating," <i>Semiconductor Fabtech - 11th Edition</i> , 273-276. 	
		Lin, Xuan et al., "Chemistry for the 0.13μm copper interconnect process," Ethone OMI, publication date unknown.	

EXAMINER SIGNATURE: 	DATE CONSIDERED: 11/14/05
<p>* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>	